Lattice Semiconductor Corporation - LC5512MV-45Q208C Datasheet

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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	4.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	16
Number of Macrocells	512
Number of Gates	-
Number of I/O	149
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc5512mv-45q208c

Product Line	Ordering Part Number	Product Status	Reference PCN
LC5512MV	LC5512MV-45Q208C	Active / Orderable	
	LC5512MV-45QN208C		
	LC5512MV-75Q208C		
	LC5512MV-75QN208C		
	LC5512MV-75Q208I		
	LC5512MV-75QN208I		
	LC5512MV-45F256C		
	LC5512MV-45FN256C		
	LC5512MV-75F256C		
	LC5512MV-75FN256C		
	LC5512MV-75F256I		
	LC5512MV-75FN256I		
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	LC5512MV-45FN484C		
	LC5512MV-75F484C		
	LC5512MV-75FN484C		
	LC5512MV-75F484I		
	LC5512MV-75FN484I		
LC5512MB	LC5512MB-45Q208C	**Discontinued**	PCN#09-10
	LC5512MB-45QN208C		
	LC5512MB-75Q208C		
	LC5512MB-75QN208C		
	LC5512MB-75Q208I		
	LC5512MB-75QN208I		
	LC5512MB-45F256C	Active / Orderable	
	LC5512MB-45FN256C		
	LC5512MB-75F256C		
	LC5512MB-75FN256C		
	LC5512MB-75F256I		
	LC5512MB-75FN256I		
	LC5512MB-45F484C	**Discontinued**	PCN#09-10
	LC5512MB-45FN484C		
	LC5512MB-75F484C		
	LC5512MB-75FN484C		
	LC5512MB-75F484I		
	LC5512MB-75FN484I		
LC5512MC	LC5512MC-45Q208C	**Discontinued**	PCN#09-10
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	LC5512MC-75Q208C		
	LC5512MC-75QN208C		
	LC5512MC-75Q208I		
	LC5512MC-75QN208I		
	LC5512MC-45F256C		
	LC5512MC-45FN256C		
	LC5512MC-75F256C		
	LC5512MC-75FN256C		
	LC5512MC-75F256I		
	LC5512MC-75FN256I		

Product Line	Ordering Part Number	Product Status	Reference PCN
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	LC5512MC-75F484C		
	LC5512MC-75FN484C		
	LC5512MC-75F484I		
	LC5512MC-75FN484I		
LC5768MV	LC5768MV-5F256C	Active / Orderable	
	LC5768MV-5FN256C		
	LC5768MV-75F256C		
	LC5768MV-75FN256C		
	LC5768MV-75F256I		
	LC5768MV-75FN256I		
	LC5768MV-5F484C		
	LC5768MV-5FN484C		
	LC5768MV-75F484C		
	LC5768MV-75FN484C		
	LC5768MV-75F484I		
	LC5768MV-75FN484I		
LC5768MB	LC5768MB-5F256C	**Discontinued**	PCN#09-10
	LC5768MB-5FN256C		
	LC5768MB-75F256C		
	LC5768MB-75FN256C		
	LC5768MB-75F256I		
	LC5768MB-75FN256I		
	LC5768MB-5F484C		
	LC5768MB-5FN484C		
	LC5768MB-75F484C		
	LC5768MB-75FN484C		
	LC5768MB-75F484I		
	LC5768MB-75FN484I		
LC5768MC	LC5768MC-5F256C	**Discontinued**	PCN#09-10
	LC5768MC-5FN256C		
	LC5768MC-75F256C		
	LC5768MC-75FN256C		
	LC5768MC-75F256I		
	LC5768MC-75FN256I		
	LC5768MC-5F484C		
	LC5768MC-5FN484C		
	LC5768MC-75F484C		
	LC5768MC-75FN484C		
	LC5768MC-75F484I		
	LC5768MC-75FN484I		

5000MX. Incoming signals may connect to the global routing pool or the registers in the MFBs. An Output Sharing Array (OSA) increases the number of I/O available to each MFB, allowing a complete function high-performance access to the I/O. There are four clock pins that drive four global clock nets within the device. Two sysCLOCK PLLs are provided to allow the synthesis of new clocks and control of clock skews.

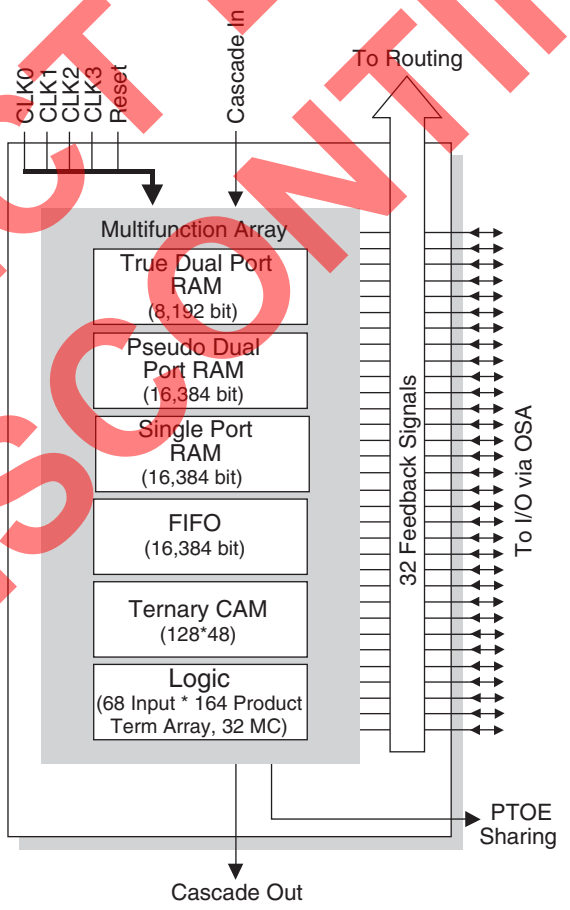
Multi-Function Block (MFB)

Each MFB in the ispXPLD 5000MX architecture can be configured in one of the six following modes. This provides a flexible approach to implementing logic and memory that allows the designer to achieve the mix of functions that are required for a particular design, maximizing resource utilization. The six modes supported by the MFB are:

- SuperWIDE Logic Mode
- True Dual-port SRAM Mode
- Pseudo Dual-port SRAM Mode
- Single-port SRAM Mode
- FIFO Mode
- Ternary CAM Mode

The MFB consists of a multi-function array and associated routing. Depending on the chosen functions the multi-function array uses up to 68 inputs from the GRP and the four global clock and reset signals. The array outputs data along with certain control functions to the macrocells. Output signals can be routed internally for use elsewhere in the device and to the sysIO banks for output. Figure 2 shows the block diagram of the MFB. The various configurations are described in more detail in the following sections.

Figure 2. MFB Block Diagram



Single-Port SRAM Mode

In Single-Port SRAM Mode the multi-function array is configured as a single-port SRAM. In this mode one ports accesses 16,384-bits of memory. Data widths of 1, 2, 4, 8, 16 and 32 are supported by the MFB. Figure 11 shows the block diagram of the single-port SRAM.

Write data, address, chip select and read/write signals are always synchronous (registered.) The output data signals can be synchronous or asynchronous. Reset is asynchronous. All signals share a common clock, clock enable, and reset. Table 7 shows the possible sources for the clock, clock enable and reset signals.

Figure 11. Single-Port SRAM Block Diagram

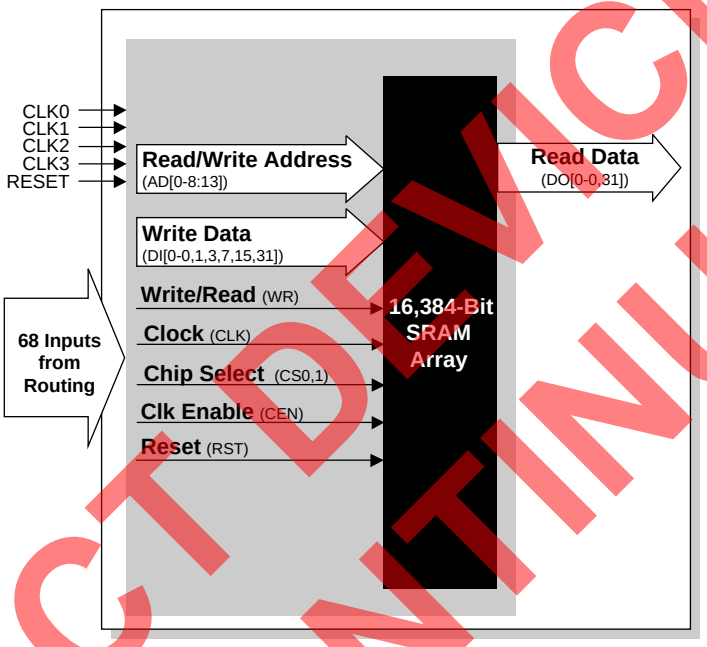


Table 7. Register Clock, Clock Enable, and Reset in Single-Port SRAM Mode

Register	Input	Source
Address, Write Data, Read Data, Read/ Write, and Chip Select	Clock	CLK or one of the global clocks (CLK0 - CLK3). Each of these signals can be inverted if required.
	Clock Enable	CEN or one of the global clocks (CLK1 - CLK 2). Each of these signals can be inverted if required.
	Reset	Created by the logical OR of the global reset signal and RST. RST is routed by the multifunction array from GRP, with inversion if desired.

CAM Mode

In CAM Mode the multi-function array is configured as a Ternary Content Addressable Memory (CAM). CAM behaves like a reverse memory where the input is data and the output is an address. It can be used to perform a variety of high-performance look-up functions. As such, CAM has two modes of operation. In write or update mode the CAM behaves as a RAM and data is written to the supplied address. In read or compare operations data is supplied to the CAM and if this matches any of the data in the array the Match and Multiple Match (if there is more than one match) flags are set to true and the lowest address with matching data is output. The CAM contains 128 entries of 48 bits. Figure 13 shows the block diagram of the CAM.

To further enhance the flexibility of the CAM a mask register is available. If enabled during updates, bits corresponding with those set to 1 in the mask register are not updated. If enabled during compare operations, bits corresponding to those set to 1 in the mask register are not included in the compare. A write don't care signal allows don't cares to be programmed into the CAM if desired. Like other write operations the mask register controls this.

The write/comp data, write address, write enable, write chip select, and write don't care signals are synchronous. The CAM Output signals, match flag, and multimatch flag can be synchronous or asynchronous. The Enable mask register input is not latched but must meet setup and hold times relative to the write clock. All inputs must use the same clock and clock enable signals. All outputs must use the same clock and clock enable signals. Reset is common for both inputs and outputs. Table 9 shows the allowable sources for clock, clock enable, and reset for the various CAM registers.

Figure 13. CAM Mode

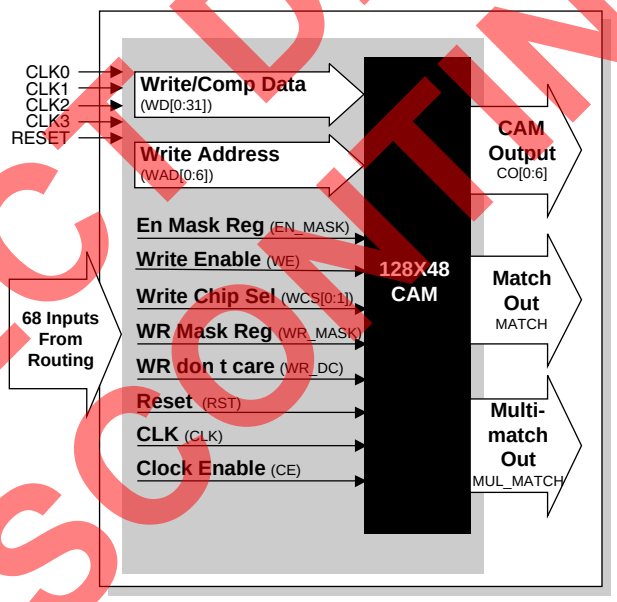


Table 9. Register Clocks, Clock Enables, and Initialization in CAM Mode

Register	Input	Source
Write data, Write address, Enable mask register, Write enable, write chip select, and write don't care, CAM Output, Match, and Multimatch	Clock	CLK or one of the global clocks (CLK0 - CLK3). Each of these signals can be inverted if required.
	Clock Enable	WE or one of the global clocks (CLK1 - CLK 2). Each of these signals can be inverted if required.
	Reset	Created by the logical OR of the global reset signal and RST. RST is routed by the multifunction array from GRP, with inversion if desired

Table 12. ispXPLD 5000MX Supported I/O Standards

sysIO Standard	Nominal V_{CCO}	Nominal V_{REF}	Nominal V_{TT}
LVTTL	3.3V	N/A	N/A
LVCMOS-3.3	3.3V	N/A	N/A
LVCMOS-2.5	2.5V	N/A	N/A
LVCMOS-1.8	1.8V	N/A	N/A
PCI 3.3V	3.3V	N/A	N/A
AGP-1X	3.3V	N/A	N/A
SSTL3, Class I & II	3.3V	1.5V	1.5V
SSTL2, Class I & II	2.5V	1.25V	1.25V
CTT 3.3	3.3V	1.5V	1.5V
CTT 2.5	2.5V	1.25V	1.25V
HSTL, Class I	1.5V	0.75V	0.75V
HSTL, Class III	1.5V	0.9V	0.75V
HSTL, Class IV	1.5V	0.9V	0.75V
GTL+	N/A	1.0V	1.5V
LVPECL, Differential	2.5V, 3.3V	N/A	N/A
LVDS	2.5V, 3.3V	N/A	N/A

Table 13. Differential Interface Standard Support[1]

		sysIO Buffer
LVDS	Driver	Supported
	Receiver	Supported with standard termination
LVPECL	Driver	Supported with external resistor network
	Receiver	Supported with termination

1. For more information, refer to TN1000 – sysIO Usage Guidelines for Lattice Devices.

Control, Clock, sysCONFIG and JTAG Signals

Global clock pins support the same sysIO standards as general purpose I/O. When required the V_{REF} signal is derived from the adjacent bank. When differential standards are supported two adjacent clock pins are paired to form the input. The TOE, PROGRAM, CFG0 and DONE pins of the ispXPLD 5000MX device are the only pins that do not have sysIO capabilities. The JTAG TAP pins support only LVCMOS 3.3, 2.5 and 1.8V standards. The voltage is controlled by V_{CCJ}. These pins only support the LVTTL and LVCMOS standards applicable to the power supply voltage of the device. The global reset global output enable pins are associated with Bank 2 and support all of the sysIO standards.

Hotsocketing

The I/O on the ispXPLD 5000MX devices are well suited for those applications that require hot socketing capability, when configured as LVCMOS or LVTTL. Hot socketing a device requires that the device, when powered down, can tolerate active signals on the I/Os and inputs without being damaged. Additionally, it requires that the effects of the powered-down device be minimal on active signals.

Programmable Drive Strength

The drive strength of I/Os that are programmed as LVCMOS is tightly controlled and can be programmed to a variety of different values. Thus the impedance an output driver can be closely match to the characteristic impedance of the line it is driving. This allows users to eliminate the need for external series termination resistors.

Programmable Slew Rate

The slew rate of outputs is carefully controlled. When outputs are configured as LVCMOS the devices support two slew rates. This allows system noise and performance to be balanced in a design.

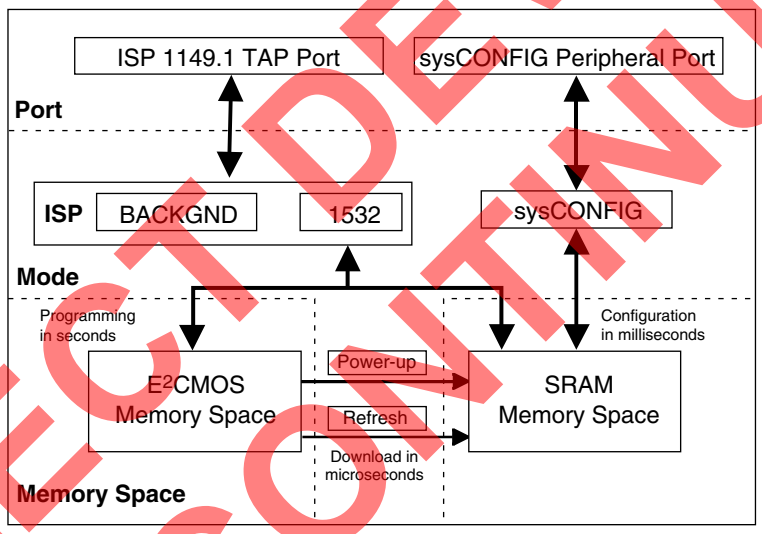
Programmable Bus-Maintenance

All general-purpose inputs have programmable bus maintenance circuitry. These are intended to maintain a valid logic level into a device when driving devices go into the tri-state mode. Four options are available for users: pull-up, pull-down, bus-keeper, or nothing.

Expanded In-System Programmability (ispXP)

The ispXPLD 5000MX family utilizes a combination of EEPROM non-volatile cells and SRAM technology to deliver a logic solution that provides “instant-on” at power-up, a convenient single chip solution, and the capability for infinite reconfiguration. A non-volatile array distributed within the device stores the device configuration. At power-up this information is transferred in a massively parallel fashion into SRAM bits that control the operation of the device. Figure 18 shows the different ports and modes that are used in the configuration and programming of the ispXPLD 5000MX devices.

Figure 18. ispXP Block Diagram



IEEE 1532 ISP

In-system programming of devices provides a number of significant benefits including rapid prototyping, lower inventory levels, higher quality and the ability to make in-field modifications. All ispXPLD 5000MX devices provide in-system programmability through their Boundary Scan Test Access Port. This capability has been implemented in a manner that ensures that the port remains compliant to the IEEE 1532 standard. By using IEEE 1532 as the communication interface through which ISP is achieved, customers get the benefit of a standard, well-defined interface.

The IEEE1532 programming interface allows programming of either the non-volatile array or reconfiguration of the SRAM bits.

The ispXPLD 5000MX devices can be programmed across the commercial temperature and voltage range. The PC-based Lattice software facilitates in-system programming of ispXPLD 5000MX devices. The software takes the JEDEC file output produced by the design implementation software, along with information about the scan chain, and creates a set of vectors used to drive the scan chain. The software can use these vectors to drive a scan chain via the parallel port of a PC. Alternatively, the software can output files in formats understood by common automated test equipment. This equipment can then be used to program ispXPLD 5000MX devices during the testing of a circuit board.

sysCONFIG Interface

In addition to being able to program the device through the IEEE 1532 interface a microprocessor style interface (sysCONFIG interface) allows reconfiguration of the SRAM bits within the device. For more information on the sysCONFIG capability, refer to TN1026, ispXP Configuration Usage Guidelines.

Security Scheme

A programmable security scheme is provided on the ispXPLD 5000MX devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit prevents readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. The security bit also prevents programming and verification. The entire device must be erased in order to erase the security bit.

Low Power Consumption

The ispXPLD 5000MX devices use zero power non-volatile cells along with full CMOS design to provide low static power consumption. The 1.8V core reduces dynamic power consumption compared with devices with higher core voltages. For information on estimating power consumption, refer to TN1031 Power Estimation in ispXPLD 5000MX Devices.

Density Migration

The ispXPLD 5000MX family has been designed to ensure that different density devices in the same package have compatible pin-outs. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

IEEE 1149.1-Compliant Boundary Scan Testability

All ispXPLD 5000MX devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic notes. Internal boundary scan registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for board-level testing. The test access port has its own supply voltage and can operate with LVCMOS3.3, 2.5 and 1.8V standards.

sysIO Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os' physical nature should be minimal so that board test time is minimized. The ispXPLD 5000MX family of devices allows this by offering the user the ability to quickly configure the physical nature of the sysIO cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice's ispVM™ System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.

Supply Current (Continued)

Symbol	Parameter	Condition	Min.	Typ.[3]	Max.	Units
ispXPLD 51024						
I_{CC}[1,2]	Operating Power Supply Current	V_{CC} = 3.3V, f = 1.0MHz	—	75	—	mA
		V_{CC} = 2.5V, f = 1.0MHz	—	75	—	mA
		V_{CC} = 1.8V, f = 1.0MHz	—	55	—	mA
I_{CCO}	Standby Power Supply Current (per I/O Bank)	V_{CCO} = 3.3V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 2.5V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 1.8V, f = 1.0MHz, unloaded	—	3	—	mA
I_{CCP}	PLL Power Supply Current (per PLL Bank)	V_{CCP} = 3.3V, f = 10MHz	—	11	—	mA
		V_{CCP} = 2.5V, f = 10MHz	—	11	—	mA
		V_{CCP} = 1.8V, f = 10MHz	—	3	—	mA
I_{CCJ}	Standby IEEE 1149.1 TAP Power Supply Current	V_{CCJ} = 3.3V	—	1	—	mA
		V_{CCJ} = 2.5V	—	1	—	mA
		V_{CCJ} = 1.8V	—	1	—	mA

1. Device configured with 16-bit counters.
2. ICC varies with specific device configuration and operating frequency.
3. T_A = 25°C

sysIO Recommended Operating Conditions

Standard	V_{CCO} (V)[2]			V_{REF} (V)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
LVCMOS 3.3	3.0	3.3	3.6	—	—	—
LVCMOS 2.5	2.3	2.5	2.7	—	—	—
LVCMOS 1.8[1]	1.65	1.8	1.95	—	—	—
LVTTL	3.0	3.3	3.6	—	—	—
PCI 3.3	3.0	3.3	3.6	—	—	—
AGP-1X	3.15	3.3	3.45	—	—	—
SSTL 2	2.3	2.5	2.7	1.15	1.25	1.35
SSTL 3	3.0	3.3	3.6	1.3	1.5	1.7
CTT 3.3	3.0	3.3	3.6	1.35	1.5	1.65
CTT 2.5	2.3	2.5	2.7	1.35	1.5	1.65
HSTL Class I	1.4	1.5	1.6	0.68	0.75	0.9
HSTL Class III	1.4	1.5	1.6	—	0.9	—
HSTL Class IV	1.4	1.5	1.6	—	0.9	—
GTL+	1.4	—	3.6	0.882	1.0	1.122
LVDS	2.3	2.5/3.3	3.6	—	—	—

1. Design tools default setting.
2. Inputs are independent of V_{CCO} setting. However, V_{CCO} must be set within the valid operating range for one of the supported standards.

ispXPLD 5000MX Family Internal Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description	Base Parameter	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
In/Out Delays													
t_{IN}	Input Buffer Delay	—	—	0.70	—	0.91	—	0.96	—	1.11	—	1.30	ns
t_{GCLK_IN}	Global Clock Input Buffer Delay	—	—	0.40	—	0.35	—	0.35	—	0.35	—	0.55	ns
t_{RST}	Global RESET Pin Delay	—	—	3.77	—	4.24	—	4.71	—	4.71	—	7.07	ns
t_{GOE}	Global OE Pin Delay	—	—	1.98	—	2.66	—	2.34	—	2.87	—	3.27	ns
t_{BUF}	Delay through Output Buffer	—	—	1.16	—	1.30	—	1.45	—	1.60	—	2.17	ns
t_{EN}	Output Enable Time	—	—	2.52	—	2.84	—	3.16	—	3.63	—	4.23	ns
t_{DIS}	Output Disable Time	—	—	1.92	—	2.40	—	2.40	—	2.40	—	3.60	ns
Routing Delays													
t_{ROUTE}	Delay through SRP	—	—	1.95	—	2.06	—	2.34	—	2.24	—	3.66	ns
t_{INREG}	Input Buffer to Macrocell Register Delay	—	—	0.60	—	0.60	—	0.60	—	0.47	—	1.63	ns
t_{PTSA}	Product Term Sharing Array Delay	—	—	0.50	—	0.50	—	0.53	—	0.83	—	1.34	ns
t_{FBK}	Internal Feedback Delay	—	—	0.19	—	0.02	—	0.39	—	0.03	—	0.60	ns
t_{GCLK}	Global Clock Tree Delay	—	—	0.52	—	0.32	—	0.72	—	0.82	—	0.78	ns
t_{BCLK}	Block PT Clock Delay	—	—	0.12	—	0.14	—	0.15	—	0.15	—	0.23	ns
t_{PTCLK}	Macrocell PT Clock Delay	—	—	0.12	—	0.14	—	0.15	—	0.15	—	0.23	ns
t_{PLL_DELAY}	Programmable PLL Delay Increment	—	—	0.30	—	0.30	—	0.30	—	0.30	—	0.30	ns
t_{BSR}	Block PT Reset Delay	—	—	0.72	—	0.81	—	0.90	—	0.94	—	1.35	ns
t_{PTSR}	Macrocell PT Set/ Reset Delay	—	—	0.60	—	0.75	—	0.75	—	0.75	—	1.13	ns
t_{LPTOE}	Macrocell PT OE Delay	—	—	0.83	—	1.19	—	1.04	—	1.52	—	1.31	ns
t_{SPTOE}	Segment PT OE Delay	—	—	0.83	—	1.19	—	1.04	—	1.52	—	1.31	ns
t_{OSA}	Output Sharing Array Delay	—	—	0.80	—	0.90	—	1.00	—	1.00	—	1.50	ns
t_{PTOE}	Global PT OE Delay	—	—	0.83	—	1.04	—	1.04	—	1.04	—	1.56	ns
t_{PDB}	5-PT Bypass Propagation Delay	—	—	0.20	—	0.23	—	0.25	—	0.25	—	0.38	ns
t_{PDI}	Macrocell Propagation Delay	—	—	0.50	—	0.93	—	0.72	—	0.72	—	1.04	ns

ispXPLD 5000MX Family Internal Switching Characteristics (Continued)

Over Recommended Operating Conditions

Parameter	Description	Base Parameter	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t_{PDPRWH}	R/W Hold time after Clock Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{PDPDATAS}$	Data Setup before Clock Time	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
$t_{PDPDATAH}$	Data Hold time after Clock Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{PDPRCLKO}$	Read Clock to Output Delay	—	—	5.08	—	5.02	—	5.66	—	5.45	—	8.54	ns
$t_{PDPCLKSKEW}$	Opposite Clock Cycle Delay	—	1.40	—	1.40	—	1.76	—	1.76	—	1.83	—	ns
$t_{PDPRSTO}$	Reset to RAM Output Delay	—	—	3.30	—	3.30	—	4.13	—	4.13	—	4.29	ns
$t_{PDPRSTR}$	Reset Recovery Time	—	1.20	—	1.20	—	1.50	—	1.50	—	1.56	—	ns
$t_{PDPRSTPW}$	Reset Pulse Width	—	0.14	—	0.14	—	0.18	—	0.18	—	0.19	—	ns
Dual Port RAM													
t_{DPMSAS}	Memory Select A Setup Before R/W A Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
t_{DPMSAH}	Memory Select Hold time after R/W A Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{DPCEAS}	Clock Enable A Setup before Clock A Time	—	3.72	—	3.72	—	3.72	—	3.72	—	4.84	—	ns
t_{DPCEAH}	Clock Enable A Hold time after Clock A Time	—	-2.95	—	-2.95	—	-2.95	—	-2.95	—	-2.27	—	ns
$t_{DPADDAS}$	Address A Setup before Clock A Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
$t_{DPADDAH}$	Address A Hold time after Clock A Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{DPRWAS}	R/W A Setup before Clock A Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
t_{DPRWAH}	R/W A Hold time after Clock A Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{DPDATAAS}$	Write Data A Setup before Clock A Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
$t_{DPDATAAH}$	Write Data A Hold time after Clock A Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
t_{DPMSBS}	Memory Select B Setup Before R/W B Time	—	-0.27	—	-0.27	—	-0.27	—	-0.27	—	-0.21	—	ns
t_{DPMSBH}	Memory Select Hold time after R/W B Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns

Signals	208 PQFP[4]	256 fpBGA[3, 5]	484 fpBGA, 5[3]	672 fpBGA[3, 5]
VCC	10, 49, 76, 114, 153, 180	D4, D13, F6, F11, L6, L11, N4, N13	A17, A6, AA2, AA21, AB17, AB6, B2, B21, D19, D4, F1, F22, G10, G11, G12, G13, K16, K7, L16, L7, M16, M7, T10, T11, T12, T13, T14, T9, U1, U22, W19, W4	AA21, AA6, F21, F6, G20, G7, J13, J14, K13, K14, L13, L14, M13, M14, N10, N11, N12, N15, N16, N17, N18, N9, P10, P11, P12, P15, P16, P17, P18, P9, R13, R14, T13, T14, U13, U14, V13, V14, Y20, Y7
VCCO0	5, 17, 189, 204	A1, F7, G6	B9, C3, G8, G9, H7, J2, J7, P4	H10, H11, H8, H9, J8, J9, K8, L8, M8, N8
VCCO1	42, 57, 72	K6, L7, T1	AA9, R7, T3, T8, Y3	P8, R8, T8, U8, V8, V9, W10, W11, W8, W9
VCCO2	85, 100, 107, 121	K11, L10, T16	AA14, R16, T15, T20, Y20	P19, R19, T19, U19, V18, V19, W12, W13, W14, W15, W16, W17, W18, W19
VCCO3	146, 161, 176	A16, F10, G11	B14, C20, G14, G15, H16, J16, J21, P19	H12, H13, H14, H15, H16, H17, H18, H19, J18, J19, K19, L19, M19, N19
VCCP	136	J16	M22	N25
VCCJ	27	J1	M1	N4
GND	15, 29, 44, 81, 119, 148, 185, 7, 19, 191, 205, 40, 56, 70, 87, 101, 109, 123, 144, 160, 174	K1, C3, C14, E5, E12, G7, G8, G9, G10, H7, H8, H9, H10, J7, J8, J9, J10, K7, K8, K9, K10, M5, M12, P3	N1, A1, A2, A21, A22, AA1, AA22, AB1, AB22, B1, B22, C15, C8, D11, D12, E18, E5, F17, F6, G16, G7, H10, H11, H12, H13, H14, H15, H20, H3, H8, H9, J10, J11, J12, J13, J14, J15, J8, J9, K10, K11, K12, K13, K14, K15, K8, K9, L10, L11, L12, L13, L14, L15, L19, L4, L8, L9, M10, M11, M12, M13, M14, M19, M4, M9, N10, N11, N12, N13, N14, N9, P10, P11, P12, P13, P14, P9, R10, R11, R12, R13, R14, R15, R8, R9, T16, T7, W11, W12, Y15, Y8	A11, A16, A2, A25, AE1, AE2, AE25, AE26, AF11, AF16, AF2, AF25, B1, B2, B25, B26, J10, J11, J12, J15, J16, J17, K10, K11, K12, K15, K16, K17, K18, K9, L1, L10, L11, L12, L15, L16, L17, L18, L26, L9, M10, M11, M12, M15, M16, M17, M18, M9, N13, N14, P13, P14, R10, R11, R12, R15, R16, R17, R18, R9, T1, T10, T11, T12, T15, T16, T17, T18, T26, T9, U10, U11, U12, U15, U16, U17, U18, U9, V10, V11, V12, V15, V16, V17
GNDP	134	K16	N22	P26
NC[2]	—	**5256MX**: A2, A11, A12, A15, B2, B12, B15, B16, C4, C12, C15, C16, D1, D11, D14, D15, D16, E1, E4, E10, E11, E13, E14, F4, F5, F12, F13, L1, L4, M3, M7, M13, N2, N6, P1, P2, P5, P6, P13, P14, P15, P16, R1, R2, R4, R5, R6, R16, T2, T3, T4, T5, T6 **5512MX/5768MX**: L1	**5512MX**: P1, AA19, AB2, AB21, J17, J6, K1, K17, K18, K19, K2, K20, K21, K22, K3, K4, K5, K6, L1, L17, L18, L2, L20, L21, L22, L3, L5, L6, M15, M17, M18, M2, M20, M21, M3, M5, M6, M8, N15, N17, N18, N19, N2, N20, N21, N3, N4, N5, N6, N8, P15, P17, P18, P2, P21, P22, P5, P6, P8, U17, U6, V18, V5, W6 **5768MX/51024MX**: None	A12, A13, A14, A15, AA10, AA11, AA12, AA13, AA14, AA15, AA16, AA17, AA7, AB10, AB11, AB12, AB13, AB14, AB15, AB16, AB17, AC10, AC11, AC12, AC13, AC14, AC15, AC16, AC17, AD11, AD12, AD13, AD14, AD15, AD16, AE11, AE12, AE13, AE14, AE15, AE16, AF12, AF13, AF14, AF15, B11, B12, B13, B14, B15, B16, C11, C12, C13, C14, C15, C16, C3, D10, D11, D12, D13, D14, D15, D16, D17, E10, E11, E12, E13, E14, E15, E16, E17, E6, E7, E8, F10, F11, F12, F13, F14, F15, F16, F17, G10, G11, G12, G13, G14, G15, G16, G17, Y10, Y11, Y12, Y13, Y14, Y15, Y16, Y17

1. All grounds must be electrically connected at the board level.
2. NC pins should not be connected to any active signals, V_{CC} or GND.
3. Balls for GND, V_{CC} and V_{CCOX} are connected within the substrate to their respective common signals. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.
4. Pin orientation follows the conventional counter-clockwise order from pin 1 marking of the topside view.
5. Internal GNDs and I/O GNDs (Bank 0 - Bank 3)þare connected inside package. V_{CCO} balls connect to four power planes within the package, one each for V_{CCOX}.

ispXPLD 5512MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	208 PQFP Pin Number	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2				
2	47N	G26	—	—	G27	108	N14	V19
—	—	GND (Bank 2)	—	—	—	109	GND (Bank 2)	GND (Bank 2)
2	48P	G28	F16	H16	G29	110	N16	T18
2	48N	G30	F17	H17	G31	111	M16	R17
2	49P	H0	F18	H18	H1	112	M14	U19
2	49N	H2	F19	H19	H3	113	M15	T19
2	50P	H4	E24	—	H5	—	—	V20
—	—	V_{CC}	—	—	—	114	VCC	VCC
2	50N	H6	E26	—	H7	—	NC	U20
2	51P	H8	F20	H20	H9	115	L13	W20
2	51N	H10	F21	H21	H11	116	L12	Y21
2	52P	H12	F22	H22	H13	117	L15	R18
2	52N	H14	F23	H23	H15	118	L16	R19
—	—	GND	—	—	—	119	GND	GND
2	53P	H16	F24	H24	H17	120	L14	W21
—	—	V_{CCO2}	—	—	—	121	V_{CCO2}	V_{CCO2}
2	53N	H18	F25	H25	H19	122	K15	Y22
—	—	GND (Bank 2)	—	—	—	123	GND (Bank 2)	GND (Bank 2)
2	54P	H20	F26	H26	H21	124	K14	R20
2	54N	H22	F27	H27	H23	125	K12	P20
2	55P	H24	F28	H28	H25	126	K13	T21
2	55N	H26	F29	H29	H27	127	J13	R21
2	56P	H28	F30	H30	H29	128	J14	U21
2	56N	H30	F31	H31	H31	129	J12	V21
—	—	TOE	—	—	—	130	J15	W22
—	—	RESET	—	—	—	131	J11	V22
—	—	GOE0	—	—	—	132	H11	T22
—	—	GOE1	—	—	—	133	H13	R22
—	—	GNDP	—	—	—	See Power Supply and NC Connections Table		
—	GCLK3N	GCLK2	—	—	—	135	H15	P16
—	—	V_{CCP}	—	—	—	See Power Supply and NC Connections Table		
—	GCLK3P	GCLK3	—	—	—	137	H16	N16
3	57N	I30	—	—	I31	138	H14	J22
3	57P	I28	—	—	I29	139	G16	H22
3	58N	I26	—	—	I27	140	G15	E22
3	58P	I24/PLL_FBK1	—	—	I25	141	F15	E21
3	59N	I22/PLL_RST1	I27	K27	I23	142	H12	G22
3	59P	I20	I26	K26	I21	143	G14	F21
—	—	GND (Bank 3)	—	—	—	144	GND (Bank 3)	GND (Bank 3)
3	60N	I18	I25	K25	I19	145	F16	H21
—	—	VCCO3	—	—	—	146	V_{CCO3}	V_{CCO3}
3	60P	I16	I24	K24	I17	147	E16	G21
—	—	GND	—	—	—	148	GND	GND

ispXPLD 5768MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Inputs	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
0	126N	S26	S13	-	S27	—	C4
0	126P	S24	S12	-	S25	—	D5

Global Clock LVDS pair options: GCLK0 and GCLK1, as well as GCLK2 and GCLK3, can be paired together to receive differential clocks; where GCLK0 and GCLK3 are the positive LVDS inputs.

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
0	175N	AC22	AC27	AE27	AC23	K6	J5
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	175P	AC20	AC26	AE26	AC21	K3	J4
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	176N	AC18	AC25	AE25	AC19	K5	K7
0	176P	AC16	AC24	AE24	AC17	K2	L7
0	177N	AC14	AC23	AE23	AC15	L5	J3
0	177P	AC12	AC22	AE22	AC13	K1	J2
0	178N	AC10	AC21	AE21	AC11	L6	K6
0	178P	AC8	AC20	AE20	AC9	L1	L6
0	179N	AC6	AC19	AE19	AC7	M5	K5
0	179P	AC4	AC18	AE18	AC5	L2	K4
0	180N	AC2	AC17	AE17	AC3	N5	K3
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	180P	AC0	AC16	AE16	AC1	L3	K2
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	181N	AE30	AC15	AE15	AE31	M6	K1
0	181P	AE28	AC14	AE14	AE29	M2	L2
0	182N	AE26	AC13	AE13	AE27	P5	L5
-	-	VCC	-	-	-	VCC	VCC
0	182P	AE24	AC12	AE12	AE25	P6	L4
0	183N	AE22	AC11	AE11	AE23	M3	L3
0	183P	AE20	AC10	AE10	AE21	N6	M3
0	184N	AE18	AC9	AE9	AE19	N2	M7
0	184P	AE16	AC8	AE8	AE17	P1	N7
-	-	GND	-	-	-	GND	GND
0	185N	AE14	AC7	AE7	AE15	N3	M5
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	185P	AE12	AC6	AE6	AE13	M8	M4
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	186N	AE10	AC5	AE5	AE11	N8	M6
0	186P	AE8	AC4	AE4	AE9	P2	N6
0	187N	AE6	AC3	AE3	AE7	P8	M2
0	187P	AE4	AC2	AE2	AE5	N4	M1
0	188N	AE2	AC1	AE1	AE3	H1	N1
0	188P	AE0	AC0	AE0	AE1	J1	N2
-	GCLK0P	GCLK0	-	-	-	N7	N5
-	-	VCCJ	-	-	-	See Power Supply and NC Connections Table	
-	GCLK0N	GCLK1	-	-	-	P7	N3
-	-	GND	-	-	-	GND	GND
-	-	TDI	-	-	-	R1	P4
-	-	TMS	-	-	-	R2	P5

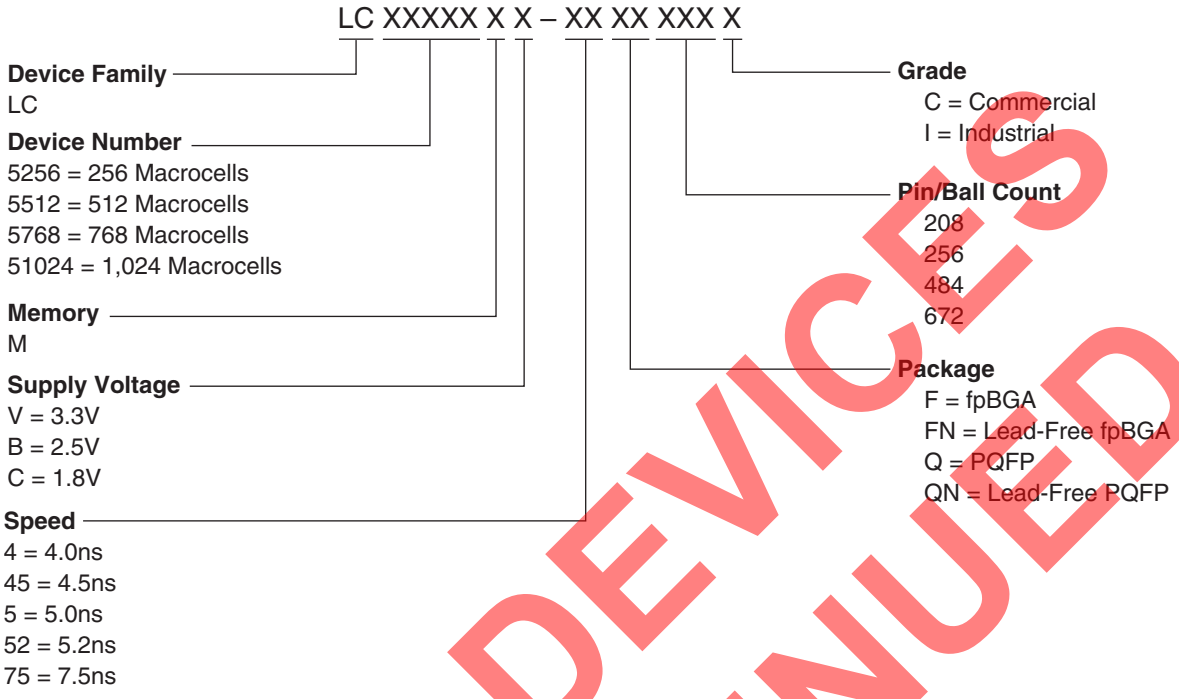
ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
1	15N	C0	A31	C31	C1	—	W5
1	16P	E30/DATA0	G0	E0	E31	W1	W1
1	16N	E28/DATA1	G1	E1	E29	Y1	Y1
1	17P	E26/DATA2	G2	E2	E27	P3	V6
1	17N	E24/DATA3	G3	E3	E25	R3	W6
1	18P	E22/DATA4	G4	E4	E23	T2	Y2
1	18N	E20/DATA5	G5	E5	E21	U2	Y3
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	19P	E18/DATA6	G6	E6	E19	V2	Y4
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	19N	E16/DATA7	G7	E7	E17	W2	Y5
-	-	GND	-	-	-	GND	GND
1	20P	E14/INITB	G8	E8	E15	R4	V7
1	20N	E12/CSB	G9	E9	E13	T4	W7
1	21P	E10/READ	G10	E10	E11	R6	AA1
1	21N	E8/CCLK	G11	E11	E9	R5	AA2
1	22P	E6	-	-	E7	U3	AA3
-	-	VCC	-	-	-	VCC	VCC
1	22N	E4	-	-	E5	V3	AA4
1	23P	E2	-	-	E3	Y2	Y6
1	23N	E0	-	-	E1	W3	AA5
1	24P	F30	H0	-	F31	U5	AB2
1	24N	F28	H2	-	F29	T5	AB3
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	25P	F26	H4		F27	U4	AB4
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	25N	F24	H6	-	F25	V4	AB5
1	26P	F22	H8	-	F23	AA3	AB1
1	26N	F20	H10	-	F21	AB3	AC2
1	-	F18	H12	-	F19	Y4	AC3
-	-	DONE	-	-	-	AA4	AC4
1	27P	F14	-	-	F15	AB2	AC1
1	27N	F12	-	-	F13	U6	AD1
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	28P	F10			F11	V5	AD2
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	28N	F8			F9	W6	AD3
1	29P	F6	G12	E12	F7	AB4	Y8
1	29N	F4	G13	E13	F5	AB5	Y9
1	30P	F2	G14	E14	F3	T6	AA8
1	30N	F0	G15	E15	F1	U7	AA9
-	-	PROGRAMB	-	-	-	W5	AB8
1	-	G28	H14	-	G29	U8	AB9

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	79N	N10	P5	N5	N11	—	V26
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	80P	N12	P6	N6	N13	—	V22
2	80N	N14	P7	N7	N15	—	V23
2	81P	N16	P8	N8	N17	—	V24
2	81N	N18	P9	N9	N19	—	V25
2	82P	N20	P10	N10	N21	—	U20
2	82N	N22	P11	N11	N23	—	T20
2	83P	N24	P12	N12	N25	—	U26
2	83N	N26	P13	N13	N27	—	U25
2	84P	N28	P14	N14	N29	—	U21
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	84N	N30	P15	N15	N31	—	T21
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	85P	P0	P16	N16	P1	—	U22
2	85N	P2	P17	N17	P3	—	U23
2	86P	P4	P18	N18	P5	—	U24
2	86N	P6	P19	N19	P7	—	T24
2	87P	P8	P20	N20	P9	—	T23
2	87N	P10	P21	N21	P11	—	T22
2	88P	P12	P22	N22	P13	—	T25
-	-	VCC	-	-	-	VCC	VCC
2	88N	P14	P23	N23	P15	—	R26
-	-	GND	-	-	-	GND	GND
2	89P	P16	P24	N24	P17	—	R25
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	89N	P18	P25	N25	P19	—	R24
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	90P	P20	P26	N26	P21	—	R21
2	90N	P22	P27	N27	P23	—	P21
2	91P	P24	P28	N28	P25	—	R22
2	91N	P26	P29	N29	P27	—	R23
2	92P	P28	P30	N30	P29	—	R20
2	92N	P30	P31	N31	P31	—	P20
-	-	TOE	-	-	-	W22	P25
-	-	RESET	-	-	-	V22	P24
-	-	GOE0	-	-	-	T22	P23
-	-	GOE1	-	-	-	R22	P22
-	-	GNDP	-	-	-	See Power Supply and NC Connections Table	
-	GCLK3N	GCLK2	-	-	-	P16	N26
-	-	VCCP	-	-	-	See Power Supply and NC Connections Table	

Part Number Description



Ordering Information

Note: For voltage families offered in industrial temperature grades and for all but the slowest commercial speed grade, the speed grades on these devices are dual marked. For example, the commercial speed grade -45XXXXC is also marked with the industrial grade -75I. The commercial grade is always one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade is marked as commercial grade only. In addition, the fastest commercial speed grade (-5) for the LC5768MB/MV devices, at Lattice's discretion, will utilize either a commercial grade only single-mark or a dual-mark format in conjunction with the slower industrial speed grade (-75).

Conventional Packaging

ispXPLD 5000MC (1.8V) Commercial Devices

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MC	LC5256MC-4F256C	256	1.8	4.0	fpBGA	256	141	C
	LC5256MC-5F256C	256	1.8	5.0	fpBGA	256	141	C
	LC5256MC-75F256C	256	1.8	7.5	fpBGA	256	141	C
LC5512MC	LC5512MC-45Q208C	512	1.8	4.5	PQFP	208	149	C
	LC5512MC-75Q208C	512	1.8	7.5	PQFP	208	149	C
	LC5512MC-45F256C	512	1.8	4.5	fpBGA	256	193	C
	LC5512MC-75F256C	512	1.8	7.5	fpBGA	256	193	C
	LC5512MC-45F484C	512	1.8	4.5	fpBGA	484	253	C
	LC5512MC-75F484C	512	1.8	7.5	fpBGA	484	253	C

ispXPLD 5000MC (1.8V) Commercial Devices (Continued)

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5768MC	LC5768MC-5F256C	768	1.8	5.0	fpBGA	256	193	C
	LC5768MC-75F256C	768	1.8	7.5	fpBGA	256	193	C
	LC5768MC-5F484C	768	1.8	5.0	fpBGA	484	317	C
	LC5768MC-75F484C	768	1.8	7.5	fpBGA	484	317	C
LC51024MC	LC51024MC-52F484C	1024	1.8	5.2	fpBGA	484	317	C
	LC51024MC-75F484C	1024	1.8	7.5	fpBGA	484	317	C
	LC51024MC-52F672C	1024	1.8	5.2	fpBGA	672	381	C
	LC51024MC-75F672C	1024	1.8	7.5	fpBGA	672	381	C

ispXPLD 5000MC (1.8V) Industrial Devices

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MC	LC5256MC-5F256I	256	1.8	5.0	fpBGA	256	141	I
	LC5256MC-75F256I	256	1.8	7.5	fpBGA	256	141	I
LC5512MC	LC5512MC-75Q208I	512	1.8	7.5	PQFP	208	149	I
	LC5512MC-75F256I	512	1.8	7.5	fpBGA	256	193	I
	LC5512MC-75F484I	512	1.8	7.5	fpBGA	484	253	I
LC5768MC	LC5768MC-75F256I	768	1.8	7.5	fpBGA	256	193	I
	LC5768MC-75F484I	768	1.8	7.5	fpBGA	484	317	I
LC51024MC	LC51024MC-75F484I	1024	1.8	7.5	fpBGA	484	317	I
	LC51024MC-75F672I	1024	1.8	7.5	fpBGA	672	381	I

ispXPLD 5000MB (2.5V) Commercial Devices

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MB	LC5256MB-4F256C	256	2.5	4.0	fpBGA	256	141	C
	LC5256MB-5F256C	256	2.5	5.0	fpBGA	256	141	C
	LC5256MB-75F256C	256	2.5	7.5	fpBGA	256	141	C
LC5512MB	LC5512MB-45Q208C	512	2.5	4.5	PQFP	208	149	C
	LC5512MB-75Q208C	512	2.5	7.5	PQFP	208	149	C
	LC5512MB-45F256C	512	2.5	4.5	fpBGA	256	193	C
	LC5512MB-75F256C	512	2.5	7.5	fpBGA	256	193	C
	LC5512MB-45F484C	512	2.5	4.5	fpBGA	484	253	C
	LC5512MB-75F484C	512	2.5	7.5	fpBGA	484	253	C
LC5768MB	LC5768MB-5F256C	768	2.5	5.0	fpBGA	256	193	C
	LC5768MB-75F256C	768	2.5	7.5	fpBGA	256	193	C
	LC5768MB-5F484C	768	2.5	5.0	fpBGA	484	317	C
	LC5768MB-75F484C	768	2.5	7.5	fpBGA	484	317	C
LC51024MB	LC51024MB-52F484C	1024	2.5	5.2	fpBGA	484	317	C
	LC51024MB-75F484C	1024	2.5	7.5	fpBGA	484	317	C
	LC51024MB-52F672C	1024	2.5	5.2	fpBGA	672	381	C
	LC51024MB-75F672C	1024	2.5	7.5	fpBGA	672	381	C